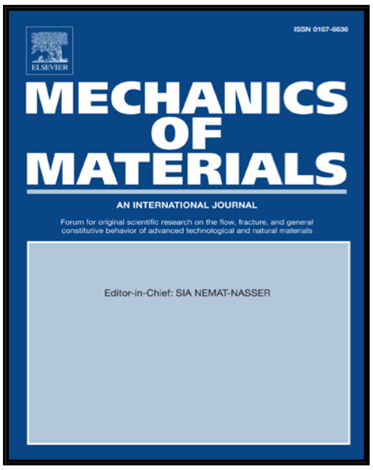

Thermomigration in SnPb solders: Material model

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Highlights

- Consistent derivation of the nonlinear fourth order formulation for thermmigration
- Phase-field model for the numerical investigation, demonstrating the applicability of finite elements
- NURBS based discretization on arbitrary shaped domains
- Computational results for thermotransport within an eutectic Sn-Pb alloy are presented